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United States Patent [19]

Farnworth et al.

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[54] **TEMPORARY PACKAGE FOR SEMICONDUCTOR DICE**

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[73] Assignee: **Micron Technology, Inc.**, Boise, Id.

[**] Term: **14 Years**

[21] Appl. No.: **70,050**

[22] Filed: **Apr. 25, 1997**

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D14/114; D13/182; 257/668, 671, 672, 693; 174/52.1–52.5; 439/55, 70; 361/718, 820

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 317,592	6/1991	Yoshizawa	D13/182
D. 359,028	6/1995	Siegel et al.	D13/182
5,053,853	10/1991	Haj-Ali-Ahmadi et al.	257/693
5,155,067	10/1992	Wood et al.	257/693 X
5,173,451	12/1992	Kinsman et al.	437/209
5,206,536	4/1993	Lim	257/668
5,302,891	4/1994	Wood et al.	324/158 F
5,408,190	4/1995	Wood et al.	324/765
5,440,240	8/1995	Wood et al.	324/765
5,442,232	8/1995	Goto et al.	257/668
5,451,165	9/1995	Cearley-Cabbiness et al.	439/71
5,455,452	10/1995	Kiyono	257/668
5,471,088	11/1995	Song	257/668
5,495,179	2/1996	Wood et al.	324/755
5,517,125	5/1996	Posedel et al.	324/755
5,519,332	5/1996	Wood et al.	324/755
5,530,376	6/1996	Lim et al.	324/765
5,541,525	7/1996	Wood et al.	324/755
5,543,725	8/1996	Lim et al.	324/755
5,581,195	12/1996	Lee et al.	324/755

OTHER PUBLICATIONS

1994 Dram Data Book, Micron Semiconductor, Inc., pp. 7–7–7–13, Apr., 1994.

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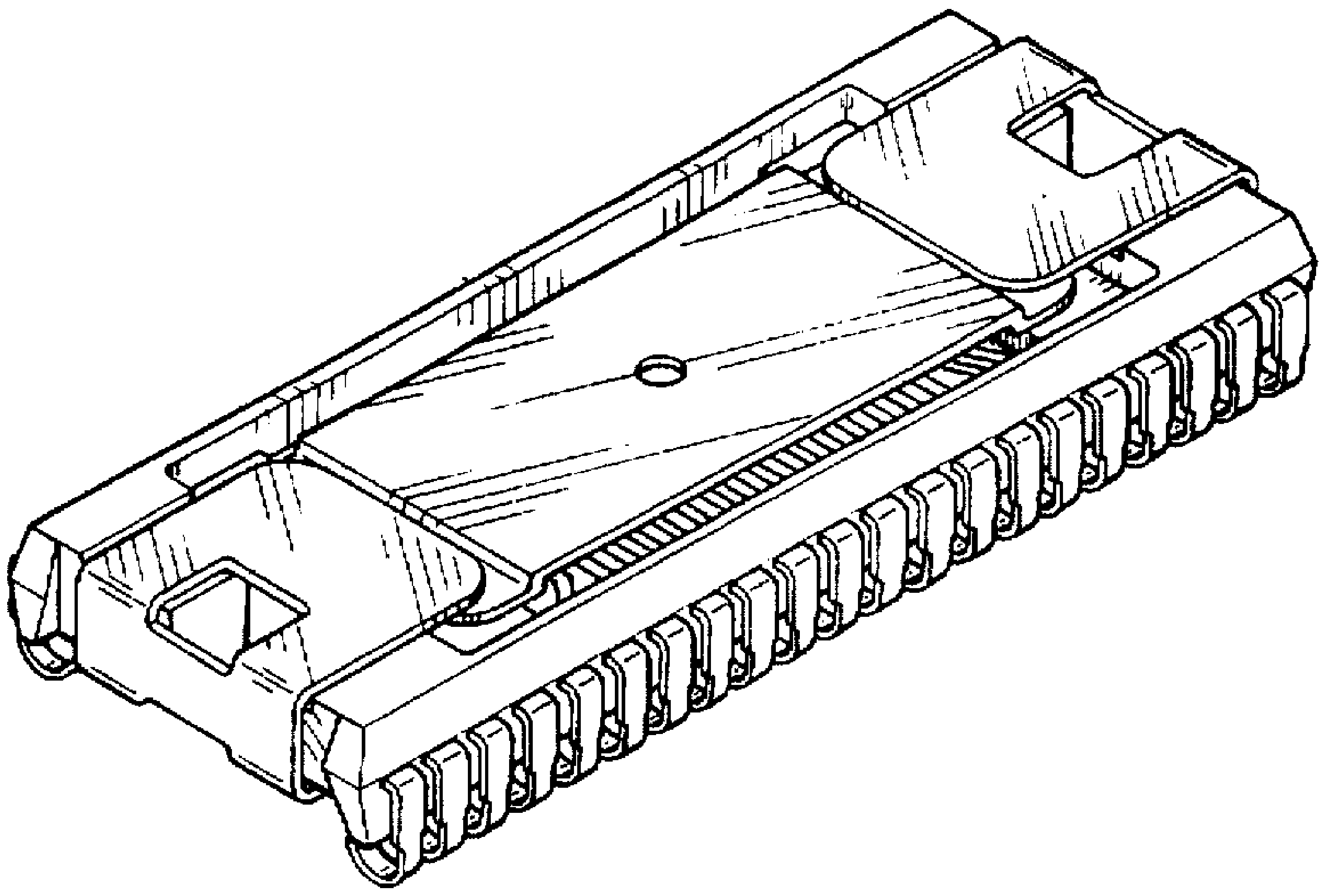
[57] **CLAIM**

The ornamental design for a temporary package for semiconductor dice, as shown and described.

DESCRIPTION

FIG. 1 is an enlarged top perspective view of a temporary package for semiconductor dice showing my new design;
FIG. 2 is a left side elevational view thereof;
FIG. 3 is a right side elevational view thereof;
FIG. 4 is a top plan view thereof;
FIG. 5 is a front side elevational view thereof;
FIG. 6 is a bottom plan view thereof; and,
FIG. 7 is a rear side elevation view thereof.

1 Claim, 2 Drawing Sheets



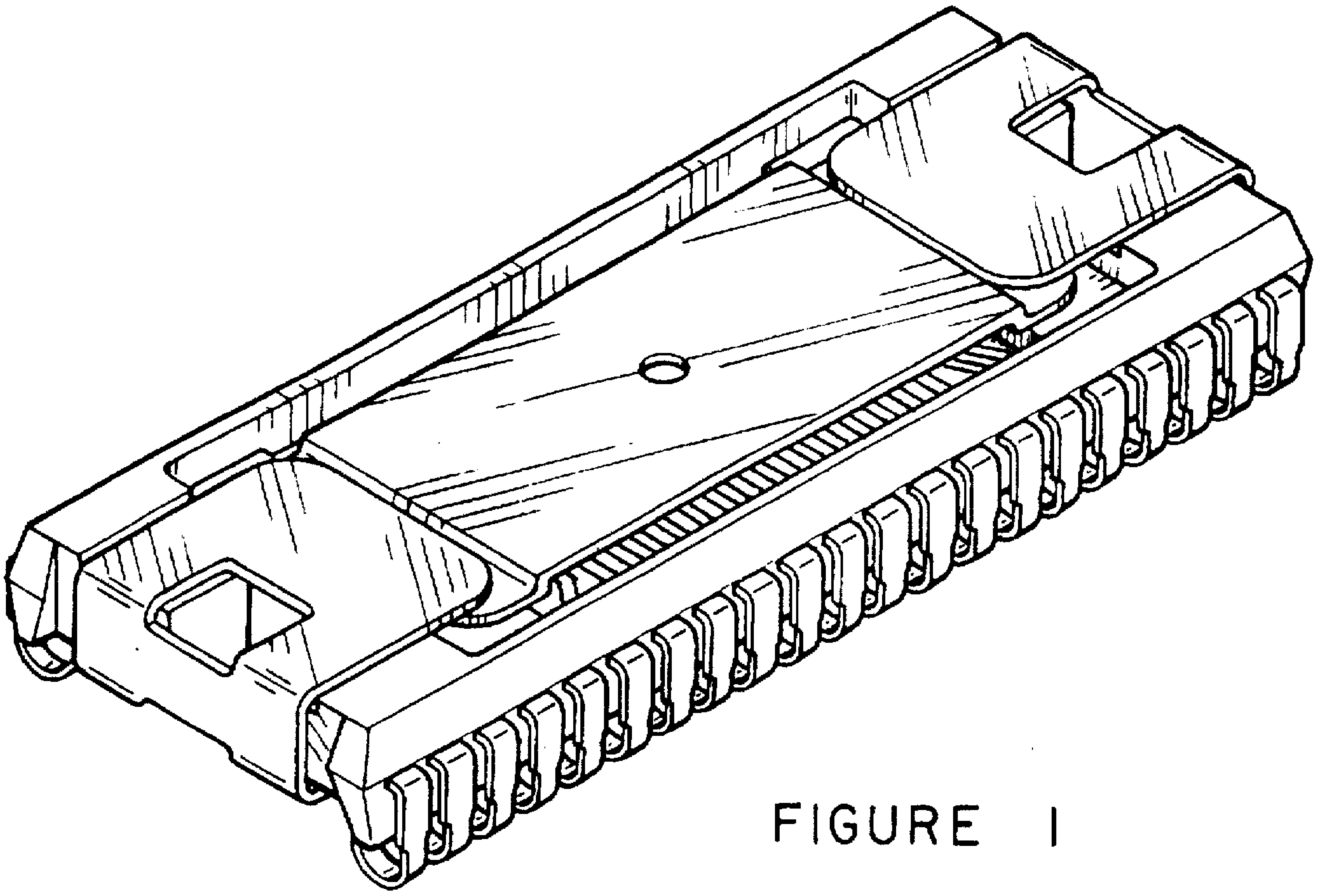


FIGURE 1

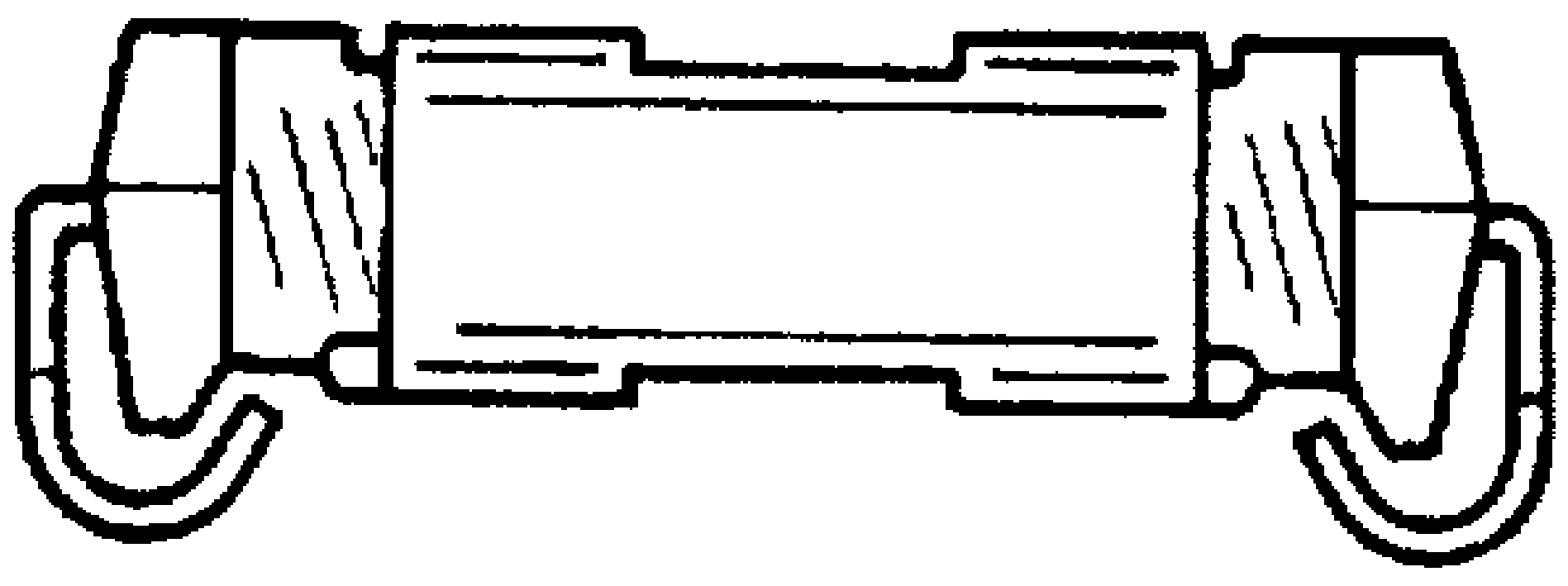


FIGURE 2

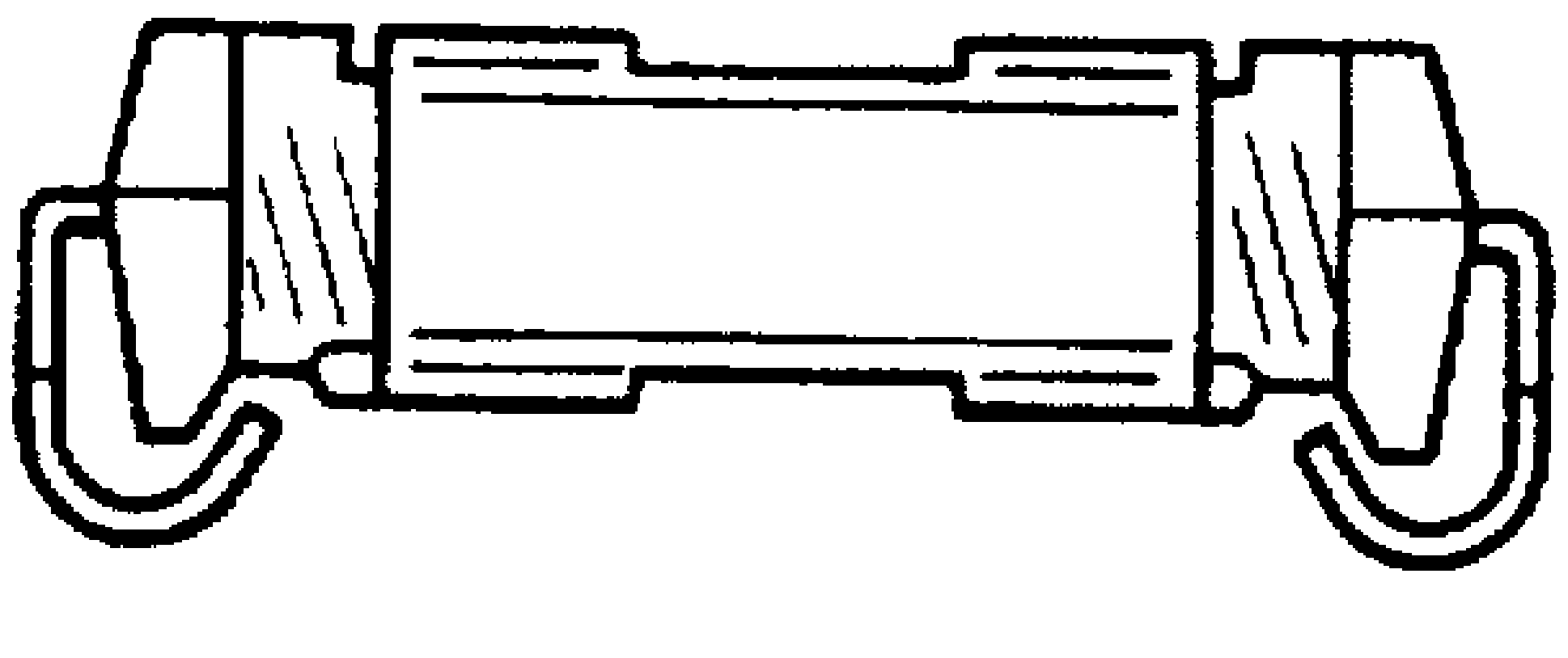


FIGURE 3

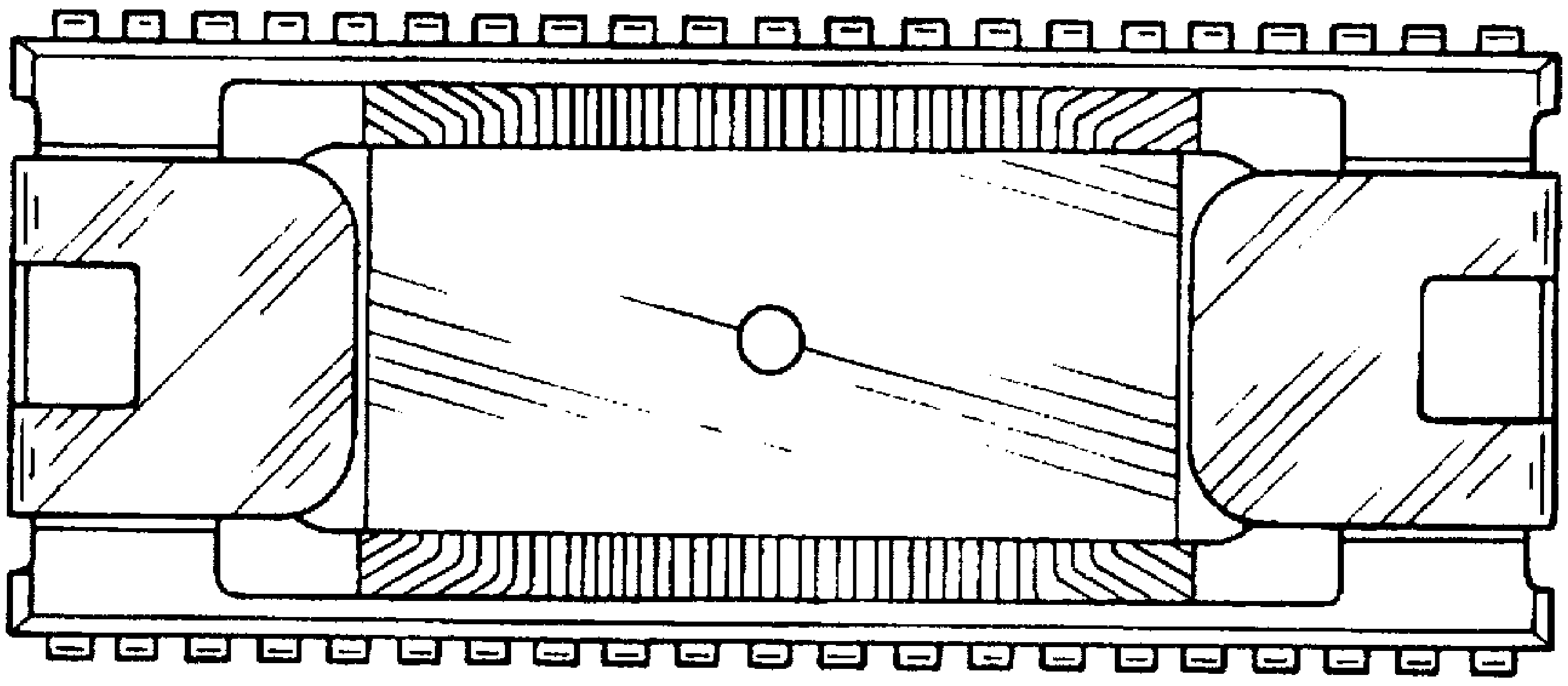


FIGURE 4

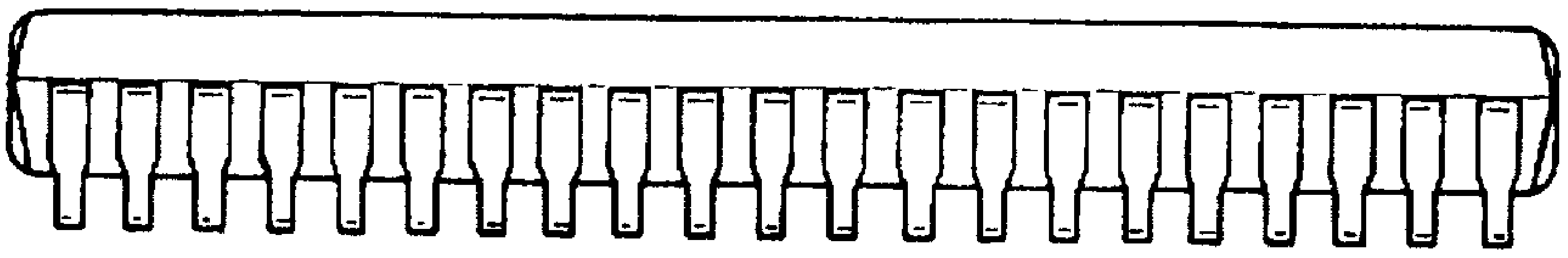


FIGURE 5

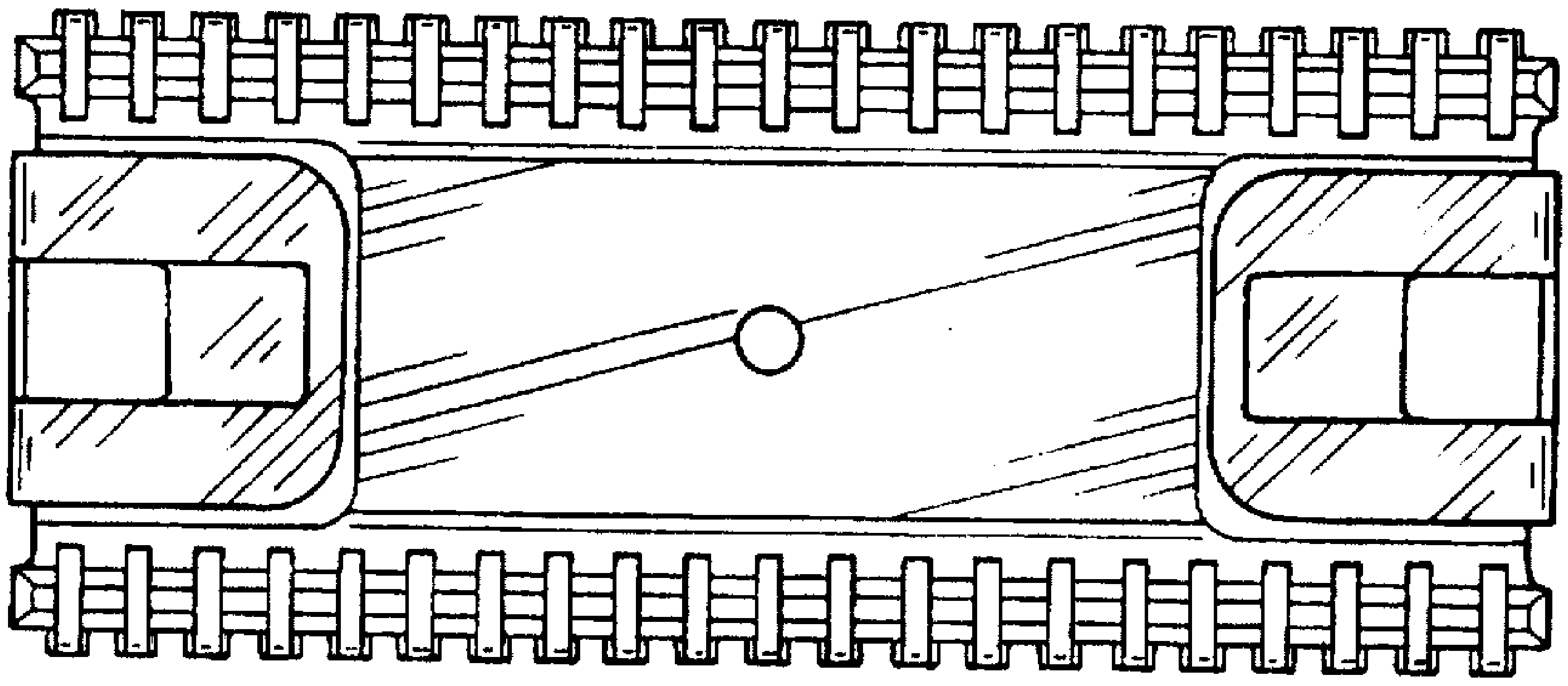


FIGURE 6

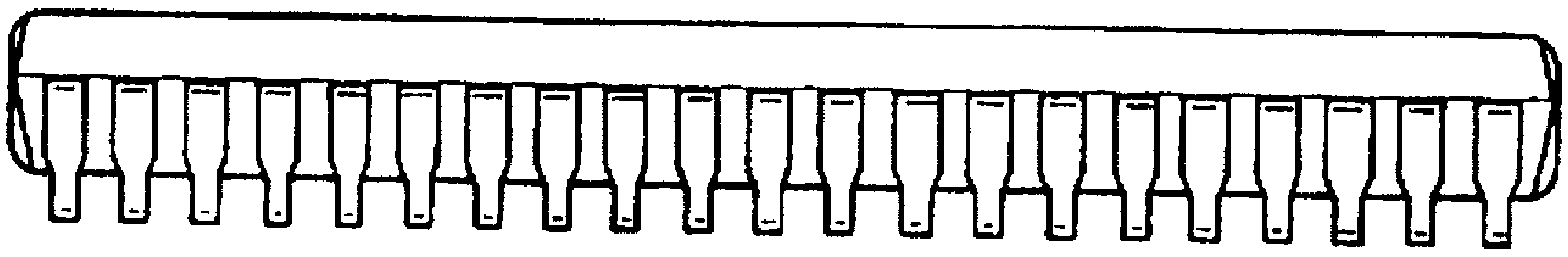


FIGURE 7